

Filename: PMP8636RevA - BoM.xls

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PMP8636REVA - SEPIC BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	150uF	Capacitor, Aluminum, 50V, 42mOhm, 1.17A, 20%	0.315 inch	EEUFM1H151	Panasonic
1	C11	1uF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
1	C12	270pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C13	220nF	Capacitor, Ceramic, 16V, X7R, 10%	0603	Std	Std
1	C14	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C15	22nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
1	C16	1nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
4	C2, C3, C4, C6	3.3uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	Std	Std
1	C5	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
4	C7, C8, C9, C10	22uF	Capacitor, Ceramic, 16V, X7R, 10%	1210	Std	Std
1	D1	MBRD660	Diode, Dual Schottky, 6A, 60V	DDPAK	MBRD660CT	On Semi
1	D101	BAS70	Diode, Dual Schottky, 70mA, 70V	SOT323	BAS70W-05-7-F	Diodes
2	J1, J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	OST
1	L1	10uH	Coupled Inductor, SMT, 10uH, 58mOhm, 10.0A sat, 2.6A rms	12.3x12.3mm	MSC1278-103M	Coilcraft
1	Q1	CSD18534Q5A	MOSFET, N-Ch, 60V, 50A, 7.8mOhm	SON 5x6	CSD18534Q5A	Texas Instruments
1	R10	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R11	4.75k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R2	226k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R3	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R4	1.00k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R5	10m	Resistor, Chip, 5W, 5%	2512	Std	Std
1	R6	6.98k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R9	49.9k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
4	TP1, TP3, TP5, TP8	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
3	TP2, TP4, TP7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	U1	TPS40210-Q1	IC, 4.5V-52V I/P, Current Mode Boost Controller	DGQ10	TPS40210-Q1	Texas Instruments

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